# MSKSEMI 美森科







TVC



TSS



MOV



GDT



PIFF

# MS3139KDFN

Product specification





#### **Features**

- $-20V,-600mA, RDS(ON) = 500m\Omega@VGS = -4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

# **Application**

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

BVDSS	RDSON	ID
-20V	500mΩ	-600mA

#### **Reference News**

PACKAGE OUTLINE	Pin Configuration	Marking
DFN1006-3	G	39

# 

Symbol	Parameter	Rating	Units
Vos	Drain-Source Voltage	-20	V
Vgs	Gate-Source Voltage	±10	V
<b>l</b> D	Drain Current - Continuous (T <sub>A</sub> =25°C)	-600	mA
טו	Drain Current - Continuous (T <sub>A</sub> =100°C)	-250	mA
Ірм	Drain Current - Pulsed <sup>1</sup>	-1.6	Α
PD	Power Dissipation (T <sub>A</sub> =25°C)	450	mW
1.0	Power Dissipation - Derate above 25°C	3.6	mW/°C
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 125	℃

#### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit
Reja	Thermal Resistance Junction to ambient		280	°C/W



# Electrical Characteristics (TJ=25 $^{\circ}$ C, unless otherwise noted) Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-20			V
△BVDSS/△TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		-0.01		V/°C
	Drain Source Leakage Current	V <sub>DS</sub> =-20V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			-1	uA
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =-16V , V <sub>GS</sub> =0V , T <sub>J</sub> =125℃			-10	uA
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =± 10V , V <sub>DS</sub> =0V			±20	uA

#### On Characteristics

			V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-0.3A		500	650	
D <sub>=</sub>		Static Drain-Source On-Resistance	V <sub>GS</sub> =-2.5V , I <sub>D</sub> =-0.2A		650	900	mΩ
IND:	R <sub>DS(ON)</sub> Static Drain-Source On-Resistance	V <sub>GS</sub> =-1.8V , I <sub>D</sub> =-0.1A		900	1400	11122	
V <sub>G</sub>	GS(th)	Gate Threshold Voltage	\/ -\/     - 050\	-0.3	-0.7	-1.0	V
۵Vc	GS(th)	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D$ =-250uA		3		mV/℃

**Dynamic and switching Characteristics** 

	<u>.                                      </u>			
Qg	Total Gate Charge <sup>2, 3</sup>		 1	
$Q_{gs}$	Gate-Source Charge <sup>2,3</sup>	$V_{DS}$ =-10V , $V_{GS}$ =-4.5V , $I_{D}$ =-0.2A	 0.28	 nC
$Q_{gd}$	Gate-Drain Charge <sup>2, 3</sup>		 0.18	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2 , 3</sup>		 8	
Tr	Rise Time <sup>2 , 3</sup>	$V_{DD}$ =-10V , $V_{GS}$ =-4.5V , $R_{G}$ =10 $\Omega$ $I_{D}$ =-0.2A	 5.2	 
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		 30	 ns
Tf	Fall Time <sup>2,3</sup>		 18	
Ciss	Input Capacitance		 40	
Coss	Output Capacitance	V <sub>DS</sub> =-10V , V <sub>GS</sub> =0V , F=1MHz	 15	 pF
C <sub>rss</sub>	Reverse Transfer Capacitance		 6.5	

#### **Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V,Force Current			-0.6	Α
Іѕм	Pulsed Source Current	VG-VD-UV , FOICE Culletil			-1.2	Α
VsD	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =-0.2A , T <sub>J</sub> =25℃			-1.3	V

#### Note:

- 1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%.
- 3. Essentially independent of operating temperature.

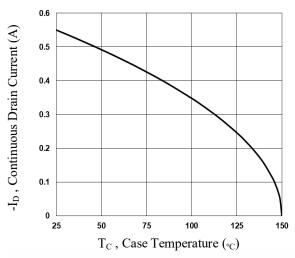


Fig.1 Continuous Drain Current vs. T<sub>c</sub>

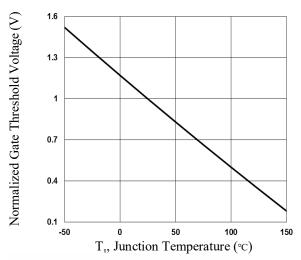


Fig.3 Normalized  $V_{th}$  vs.  $T_J$ 

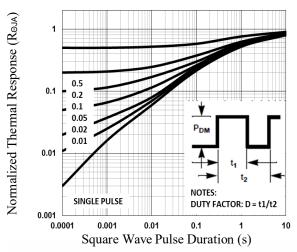


Fig.5 Normalized Transient Response

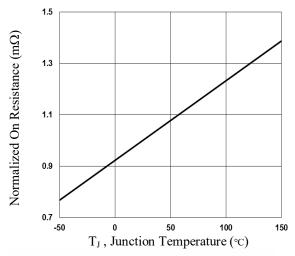


Fig.2 Normalized RDSON vs. T<sub>J</sub>

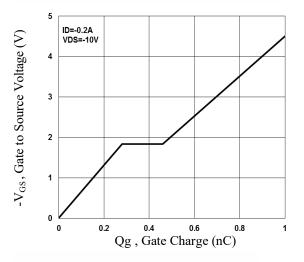


Fig.4 Gate Charge Waveform

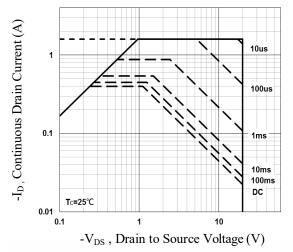
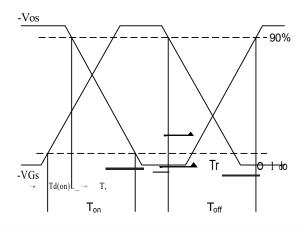


Fig.6 Maximum Safe Operation Area





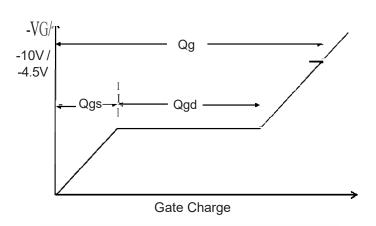
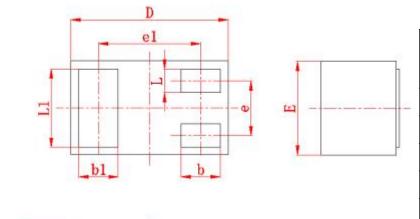


Fig.8 Gate Charge Waveform

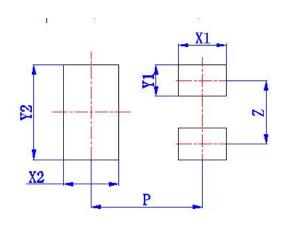


# Package mechanical data



Company of	Millimeters			
Symbol	min	max		
А	0.4	0.5		
A1	0	0.05		
D	0.9	1.1		
E	0.55	0.65		
е	(0.35)			
e1	(0.	65)		
b	0.2	0.3		
b1	0.2	0.3		
L	0.1 0.2			
L1	0.45 0.55			

# Suggested Land Pattern



Symbol	Dimension in Millimeters		
Symbol	typ		
X1	(0.3)		
X2	(0.35)		
Y1	(0.2)		
Y2	(0.6)		
Z	(0.4)		
Р	(0.7)		

### **REEL SPECIFICATION**

P/N	PKG	QTY
MS3139KDFN	DFN1006-3	10000



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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP NTMC083NP10M5L BXP7N65D BXP4N65F AOL1454G
WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13
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